Product Change Notification - JAON-22VBSE169

Date: 11 Aug 2017

Product Category: Interface- LIN Transceiver; Interface- Controller Area Network (CAN); Piezoelectric Horn Drivers

Notification subject: CCB 2543 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for products fabricated at XFGM available in 8L SOIC package at MMT assembly site.

Notification text:

PCN Status:
Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for products fabricated at XFGM available in 8L SOIC package at MMT assembly site.

Pre Change:
Gold (Au) bond wire

Post Change:
Palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MMT assembly site	MMT assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8390A or 2200D	8390A
Molding compound material	G600V	G600V
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity and qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:
In Progress

Estimated First Ship Date:
September 8, 2017 (date code: 1736)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

	March 2016					**->**	**August 2017**				**September 2017**				
WW	09	10	11	12	13		31	32	33	34	35	36	37	38	39
Initial PCN Issue Date	X														
Qual Report Availability								X							
Final PCN Issue Date								X							
Implementation Date												X			

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
March 2, 2016: Issued initial notification.
August 11, 2017: Issued final notification. Attached the qualification report. Revised the estimated first ship date from June 30, 2016 to September 8, 2017.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-22VBSE169_Qual Report.pdf
PCN_JAON-22VBSE169_Affected CPN.pdf
PCN_JAON-22VBSE169_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-22VBSE169
CATALOG_PART_NBR
MCP2025-330E/SN
MCP2025-500E/SN
MCP2025T-330E/SN
MCP2025T-500E/SN
MCP2551-E/SN
MCP2551-I/SN
MCP2551T-E/SN
MCP2551T-I/SN
RE46C108S8F
RE46C108S8TF
RE46C117S8F
RE46C117S8TF
RE46C317S8F
RE46C317S8TF
RE46C318S8F
RE46C318S8TF